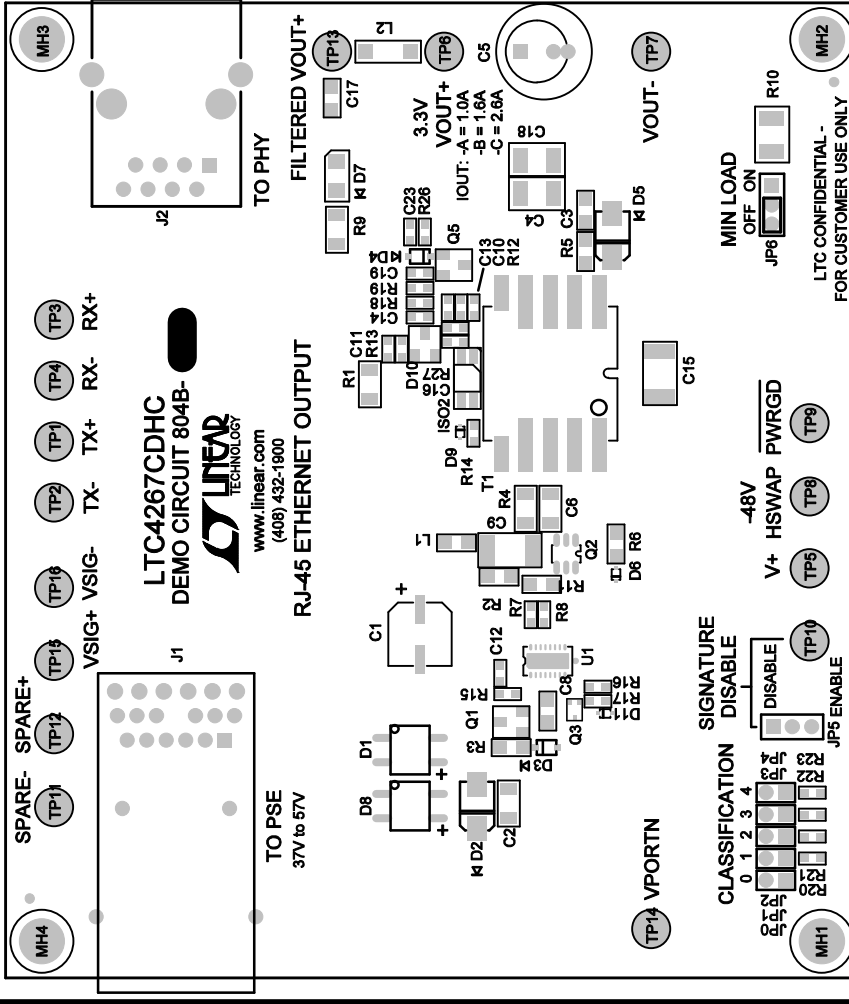


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
	1	REBUILD WITH CHANGES	KAUNG H.	02/17/11



- NOTES: UNLESS OTHERWISE SPECIFIED,
1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
 2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SMD. MAXIMUM SOLDER TEMPERATURE, 240 DEG. C.
 3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
 4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
 5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
 6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
 7. INSTALL TURRETS AS SHOWN.
 8. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN.
 9. INSTALL D7 AS SHOWN.



APPROVALS		LTC4267CDHC		RJ-45 ETHERNET OUTPUT	
PCB DES.	MI	SIZE	IC NO.	REV	
APP. ENG.	KAUNG H.	N/A	LTC4267CDHC	1	
			DEMO CIRCUIT 804B		
SCALE: NONE		FILENAME: 804b-1.PCB		SHT 1 of 2	



TITLE: TOP ASSEMBLY DRAWING,

RJ-45 ETHERNET OUTPUT

SIZE	IC NO.	REV
N/A	LTC4267CDHC	1
	DEMO CIRCUIT 804B	

FILENAME: 804b-1.PCB

SCALE: NONE

APPROVALS

PCB DES. MI

APP. ENG. KAUNG H.

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